



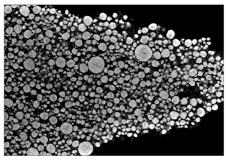
# The workhorse for your research

ZEISS X-ray microscopes (XRM) are advanced research solutions that have removed major technological hurdles for 3D imaging by achieving high contrast and submicron resolution even for relatively large samples. ZEISS Xradia 515 Versa uses a two-stage magnification technique that enables you to uniquely achieve resolution at a distance (RaaD). Combined with the flexibility and stability of the ZEISS Xradia platform, this unparalleled versatility delivers a fast time to results for your research.

These ground-breaking advances in non-destructive 3D imaging empower a breadth of technical disciplines with a diverse range of sample sizes, geometries and compositions. The versatility of the platform enables unique applications like interior tomography, phase contrast, 4D, and high resolution *in situ* imaging.

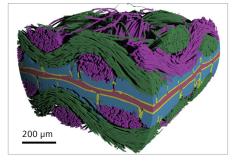
ZEISS 3D X-ray microscopes are built on upgradeable, extensible, and reliable platforms that help protect your capital investment.

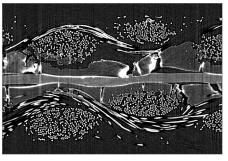
100 μm



ZEISS Xradia 515 Versa is the foundation of the Xradia Versa family for those who simply need the best 3D imaging capability.

3D rendering (left) and virtual cross section (right) of a section of a lithium ion battery cathode showing the particles that comprise the electrode, as well as internal particle cracking





3D rendering (left) and virtual cross section (right) of a polymer electrolyte fuel cell showing gas diffusion layer fibers (purple/green), microporous layer (blue), catalyst layer (yellow), and electrolyte (orange)



lmaging	ZEISS Xradia 410 Versa	ZEISS Xradia 515 Versa	ZEISS Xradia 610 Versa	ZEISS Xradia 620 Versa
Spatial Resolution <sup>[a]</sup>	0.9 μm	0.5 μm	0.5 μm	0.5 μm
lesolution at a Distance (RaaD) <sup>[a,b]</sup>	1.5 µm	1.0 µm	1.0 µm	1.0 µm
Minimum Achievable Voxel (c)  Voxel size at sample at maximum magnification)	100 nm	40 nm	40 nm	40 nm
K-ray Source				
Architecture	Sealed Reflection	Sealed Transmission	Sealed Transmission,	Sealed Transmission,
			Fast Activation	Fast Activation
/oltage Range	20 – 90 kV	30 – 160 kV	30 – 160 kV	30 – 160 kV
Maximum Output	8 W	10 W	25 W	25 W
Detector System				
ZEISS X-ray microscopes feature an innovative detector tur	ret with multiple objectives at different r	magnifications. Each objective feat	ures optimized scintillators that d	eliver the highest absorption
contrast details.				
Standard Objectives	0.4x, 4x, 10x, 20x	0.4x, 4x, 20x	0.4x, 4x, 20x	0.4x, 4x, 20x
Optional Objectives	40x	40x, Flat Panel Extension (FPX)	40x, Flat Panel Extension (FPX)	40x, Flat Panel Extension (FPX
Stages				
ample Stage (load capacity)	25 kg	25 kg	25 kg	25 kg
ample Stage Travel (x, y, z)	50, 100, 50 mm	50, 100, 50 mm	50, 100, 50 mm	50, 100, 50 mm
ample Size Limit	300 mm diameter	300 mm diameter	300 mm diameter	300 mm diameter
Features				
Scout-and-Scan Control System				
Scout-and-Zoom				
ertical Stitch				
(RM Python API				
EISS SmartShield			•	
Automated Filter Changer (AFC)				
ligh Aspect Ratio Tomography (HART)				•
Dual Scan Contrast Visualizer (DSCoVer)				
EISS LabDCT for Diffraction Contrast Tomography				Optional
Vide Field Mode	0.4x	0.4x	0.4x	0.4x and 4x
GPU CUDA-based Reconstruction	Single	Single	Dual	Dual
EISS Autoloader	Optional	Optional	Optional	Optional
n Situ Interface Kit	Optional	Optional	Optional	Optional
EISS DeepRecon Pro	Optional	Optional	Optional	Optional
EISS OptiRecon	Optional	Optional	Optional	Optional
EISS PhaseEvolve	Optional	Optional	Optional	Optional
ZEISS ZEN Intellesis	Optional	Optional	Optional	Optional
DRS Dragonfly Pro	Optional	Optional	Optional	Optional

🛮 Voxel size is a geometric term that contributes to but does not determine resolution, and is provided here only for comparison. ZEISS specifies resolution via spatial resolution,

# Benefits

■ Non-destructive 3D imaging

the true overall measurement of instrument resolution.

- Highest resolution at the largest working distance with unique RaaD (Resolution at a Distance) capability
- Multi-length scale imaging of the same sample across a wide range of magnifications
- Advanced contrast solutions, including absorption and phase contrast
- Industry-leading 4D and *in situ* capabilities for flexible sample sizes and types
- SmartShield for sample protection and setup optimization
- Scout-and-Scan control system for easy-to-use workflow set-up, ideal in multi-user environments
- Automated precision sample positioning for seamless3D imaging and navigation
- Program up to 14 samples at a time to run sequentially with optional Autoloader
- Expand the field of view (FOV) to image larger samples with optional Flat Panel Extension (FPX)
- XRM Python API for customized instrument control
- Continuous access to advanced reconstruction technologies such as OptiRecon and DeepRecon Pro for enhanced performance (e.g., up to 10x throughput, superior image quality)











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### **Field of Application**

# **Materials Research**

Characterize materials in 3D, observe failure mechanisms and degradation, investigate properties at multiple length scales, quantify and analyze microstructural evolution with 4D and *in situ* studies.

# **Battery and Energy Storage**

Failure analysis, quality inspection of separator and electrodes for defects and inclusions, track aging mechanisms.

### **Electronics and Semiconductor**

Image and characterize regions of interest during failure analysis on intact packages before cutting or polishing.

#### **Natural Resources**

Characterize and quantify pore structures, measure fluid flow, acquire multi-phase particle information and large volume statistics for oil and gas, mining, and other natural resources requirements.

### Manufacturing Technology

Analyze internal tomographies of 3D printed parts, perform *in situ* mechanical testing.

# **Life Sciences**

Visualize and characterize tissues, cells, and microstructures within entire plants and fixed small animal models.